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1 Introduction

Triple modular redundancy (TMR) is a technique commonly used to provide design hardening. Previous studies have shown that a feedback style of TMR[1] will ensure the reliability of designs in the presence of single event upsets (SEUs)[2]. This previous work showed that reliability comes at the cost of at least 3x in design area (sometimes as much as 6x) and at the cost of reduced clock rates. Another, perhaps more important cost consideration is the increase in power consumption due to TMR. This study investigates the cost of TMR in terms of power consumption on different Xilinx FPGA architectures. In this study we use a more classical TMR style rather than the selective feedback style. Xilinx's XPower power estimation tool[3] as well as ISI's SLAAC1V[4] board power measurement tool allow us to accurately estimate and measure the power consumed by various designs. The results of this study show that the choice of FPGA architecture greatly affects the amount of power consumption. The study also shows that design placement also affects how much power is consumed.

2 Power Measurement and Estimation Calibration

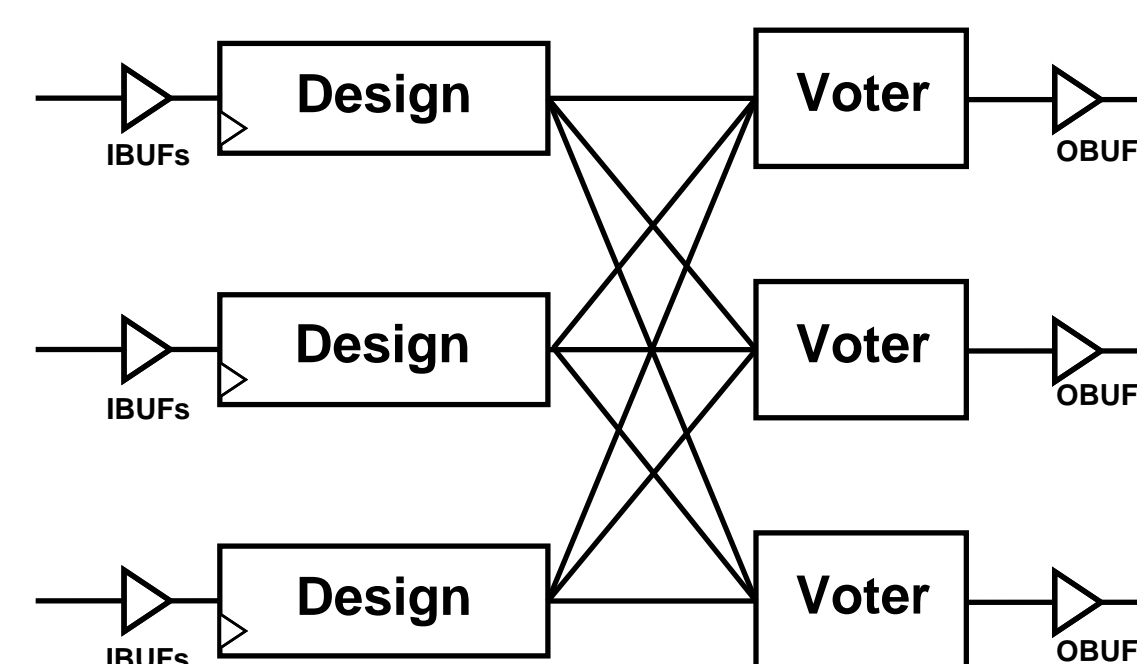
JPower

- Current measuring tool for the SLAAC1V Board (Virtex only)
- Tool made functional at LANL by Jared Zimmerman
- 2.5 V channel sampled at 120 kHz
- Current stored as 10-bit number then multiplied by 4.8828125 mA
- Current measurements up to 4990 mA

XPower

- Xilinx power measurement tool
- ModelSim *.vcd files and timing information required

Classic TMR

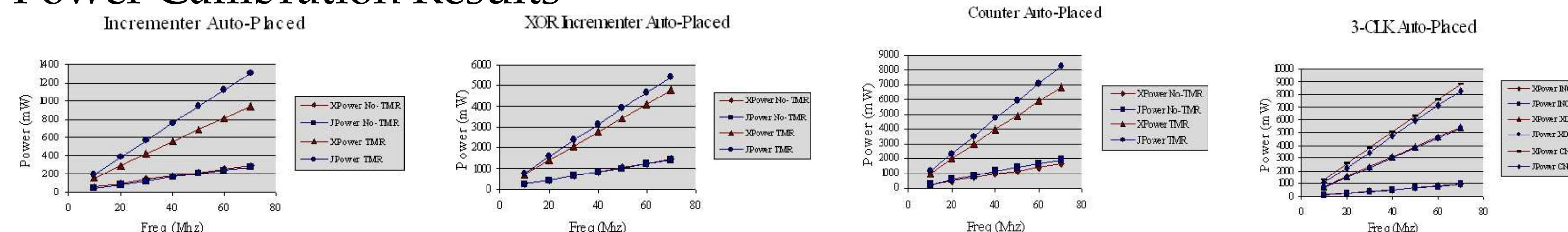


- TMR applied at top level
- Top level IBUFs and OBUFs also triplicated
- Our studies used this style of TMR

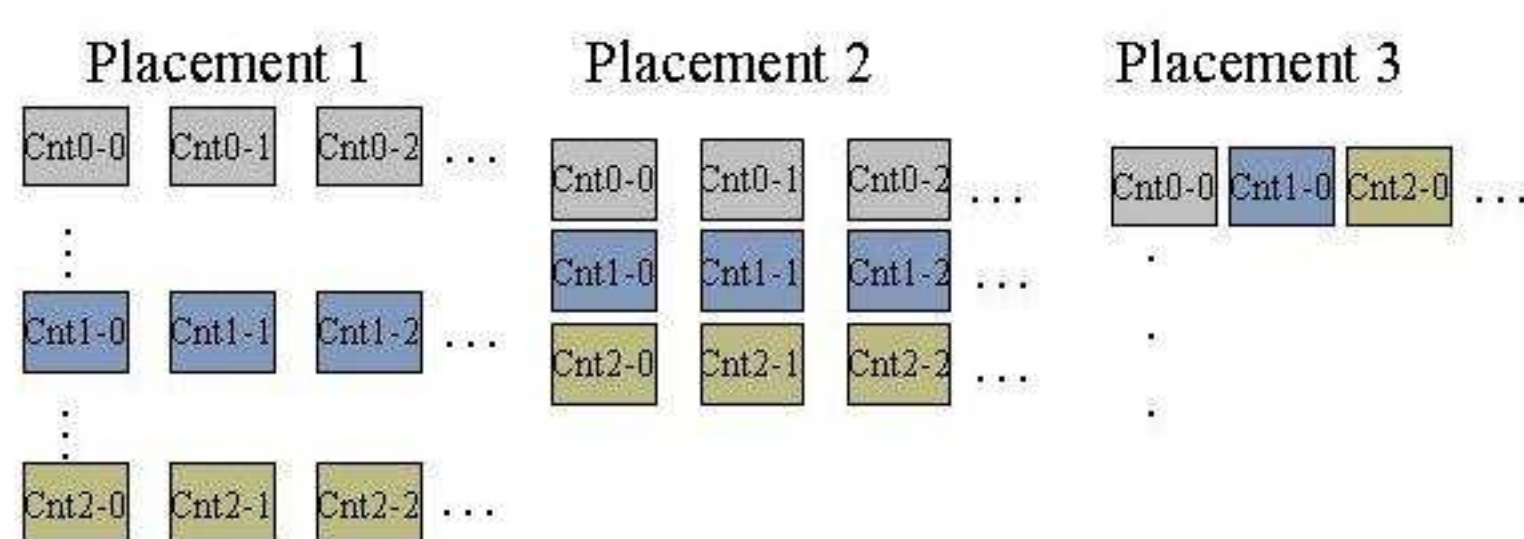
Calibration Designs

- **72 Incrementers** - each output leading to an IOB
- **416 Incrementers** - outputs grouped into XOR gates leading to IOBs
- **416 Up/down loadable counters** - final counter output leading to IOBs
- The above 3 designs but with **triplicated clocks**

Power Calibration Results



3 Effects of Placement on Power Consumption



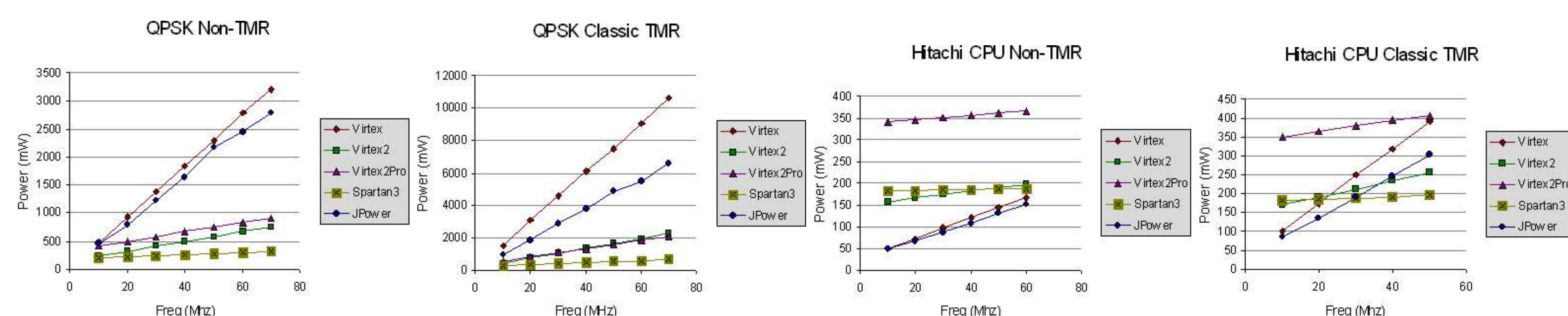
- Placement studies primarily done on **72 incrementer** design
- Xilinx auto-placement and 3 hand placements considered
- Only auto-placement and one hand placement considered for other designs

Incrementer				
	Auto-Place	Place 1	Place 2	Place 3
Frequency vs. Power Slopes (TMR)				
JPower	7.37	10.65	6.15	4.76
XPower	5.23	6.20	5.21	4.78
Power Increase Due to TMR				
JPower	4.79x	7.04x	4.06x	3.15x
XPower	3.40x	4.04x	3.39x	3.10x

	Incrementer		XOR Incrementer		Up/Down Counter	
	Auto-Place	Hand-Place	Auto-Place	Hand-Place	Auto-Place	Hand-Place
Frequency vs. Power Slopes						
JPower	7.37	4.78	31.13	22.18	47.53	41.22
XPower	5.23	4.76	27.06	25.10	39.03	36.40
JP / XP	1.41	1.00	1.15	0.88	1.22	1.13

4 Power Costs of Realistic Designs on Different Xilinx Architectures

Power Consumption Results



	Non-TMR					TMR				
	JPower	Virtex	Virtex2	Virtex2Pro	Spartan3	JPower	Virtex	Virtex2	Virtex2Pro	Spartan3
Frequency vs. Power Slopes										
QPSK	40.50	45.71	8.60	8.16	1.97	93.75	150.64	30.17	24.98	6.68
Hitachi	2.06	2.34	0.79	0.48	0.12	5.48	7.30	2.10	1.39	0.30

	QPSK Demodulator		Hitachi CPU	
	TMR Area Cost	TMR Speed Cost	TMR Power Cost	
Virtex	3.03x	95.2%	3.30x	3.01x
	3.03x	84.6%	3.51x	3.00x
	3.03x	77.9%	3.06x	3.00x
Virtex2	3.03x	77.9%	3.06x	3.00x
	3.03x	77.9%	3.06x	3.00x
	3.03x	77.9%	3.06x	3.00x
Virtex2Pro	3.03x	77.9%	3.06x	3.00x
	3.03x	77.9%	3.06x	3.00x
	3.03x	77.9%	3.06x	3.00x
Spartan3	3.03x	77.9%	3.06x	3.00x
	3.03x	77.9%	3.06x	3.00x
	3.03x	77.9%	3.06x	3.00x

5 Conclusion

- Power increase to TMR is 3x (can be more with poor design placement)
- FPGA architecture significantly affects power consumption

References

- [1] Carl Carmichael. Triple module redundancy design techniques for Virtex FPGAs. Technical report, Xilinx Corporation, November 1, 2001. XAPP197 (v1.0).
- [2] Nathan Rollins, Michael Wirthlin, Michael Caffrey, and Paul Graham. Evaluating tmr techniques in the presence of single event upsets. In *Proceedings of the 6th Annual International Conference on Military and Aerospace Programmable Logic Devices (MAPLD)*, September 2003. To Be Published.
- [3] Xilinx, Inc. *XPower Manual*.
- [4] USC-ISI East. *SLAAC-1V User VHDL Guide*, October 1, 2000. Release 0.3.1.